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(19) **United States**(12) **Patent Application Publication****KALLMARK et al.**(10) **Pub. No.: US 2022/0361372 A1**(43) **Pub. Date: Nov. 10, 2022**(54) **HEATSINK WITH INCREASED AIR FLOW****Publication Classification**(71) Applicant: **HUAWEI TECHNOLOGIES CO., LTD.**, Shenzhen (CN)(51) **Int. Cl.**
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The invention relates to a heatsink for transferring heat from one or more electrical devices to a heat transfer medium. The heatsink includes a plurality of fins arranged on a frontside of the heatsink. The plurality of fins includes a first group of fins extending in a first planar direction and a second group of fins extending in a second planar direction angled in relation to the first planar direction. For example, the first group of fins may extend from the bottom to the top of the heatsink, while the second group of fins may extend from the first group of fins to the sides of the heatsink. In this way, the sides of the heatsink can be used as air outlets and the airflow through the heatsink can be increased.

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